

# AQ7-IMX6

## Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> _____			
	<b>Test Result Summary</b>			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date	Approval	Test Engineer
2014 / 03 / 05	Tom Lin	Ben Sun

## Sample Configuration & Quantity Under Test

- Model name : AQ7-IMX6 A0.2 + ECB-970 A0.2
- CPU Board : AQ7-IMX6
- CPU : Onboard FreescaleR i.MX6 Quad ARM Cortex A9 1.0GHz
- Memory : Onboard DDR3 533MHz
- Test Software : Android 4.0.4 / Run Stability Test v2.7
- Power : ATX Power (DSA400P-C)
- Heat Sink :



# Thermal Image Analysis

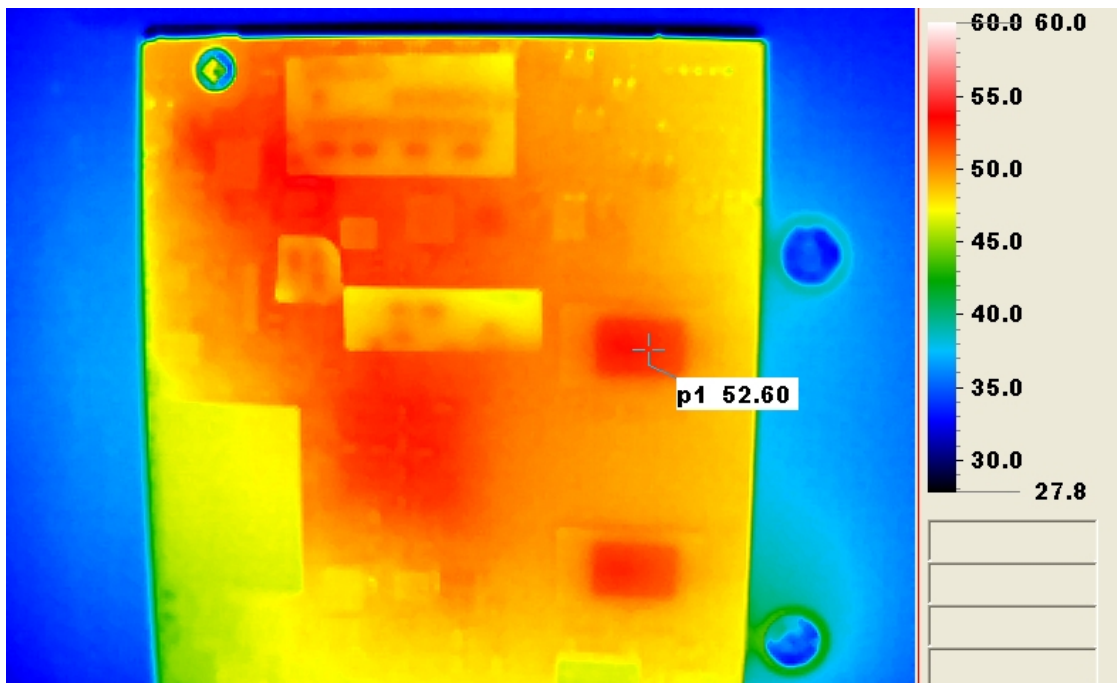
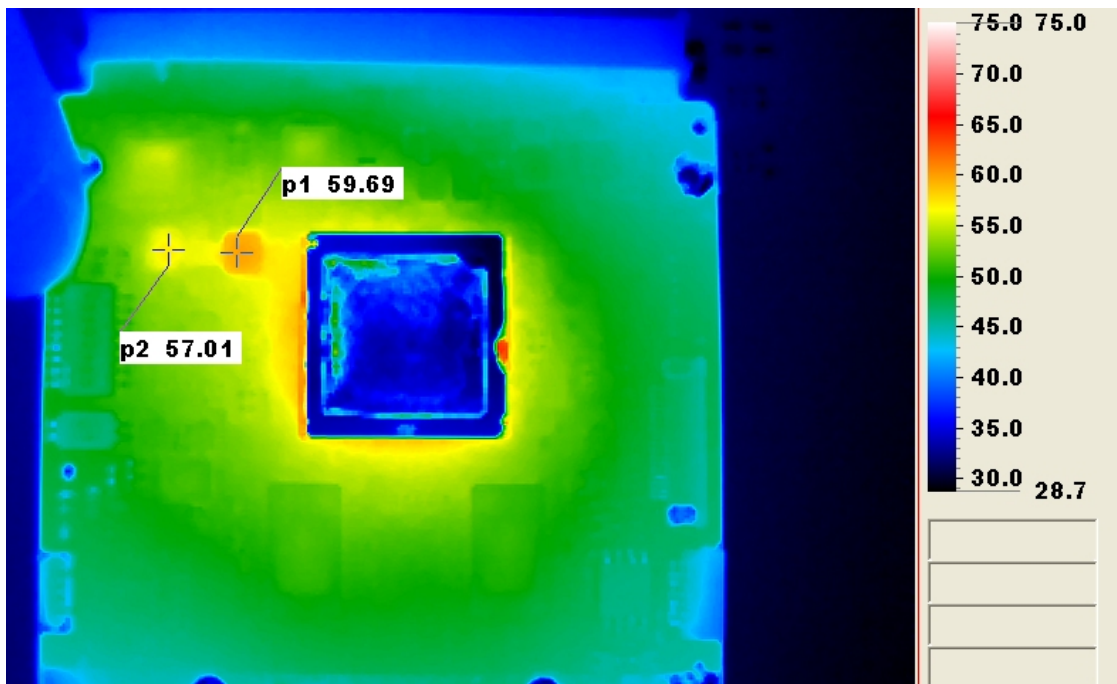
1. Test Date: 2014-03-04
2. Test Product: AQ7-IMX6 A0.2 with ECB-970
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
  - 4.1. 40 Channel Thermal Recorder:
    - 4.1.1 YOKOGAWA Inc,
    - 4.2.2 Model: DA100-13-1D  
Date of Calibration: 2013/10/01  
Serial Number: 12A323190
  - 4.2. IR Scanner: Infrared Camera
    - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
    - 4.2.2 Model: Thermo GEAR G100W2-D  
Date of Calibration: 2013/12/30  
Serial Number: 1051444
5. Test Condition:

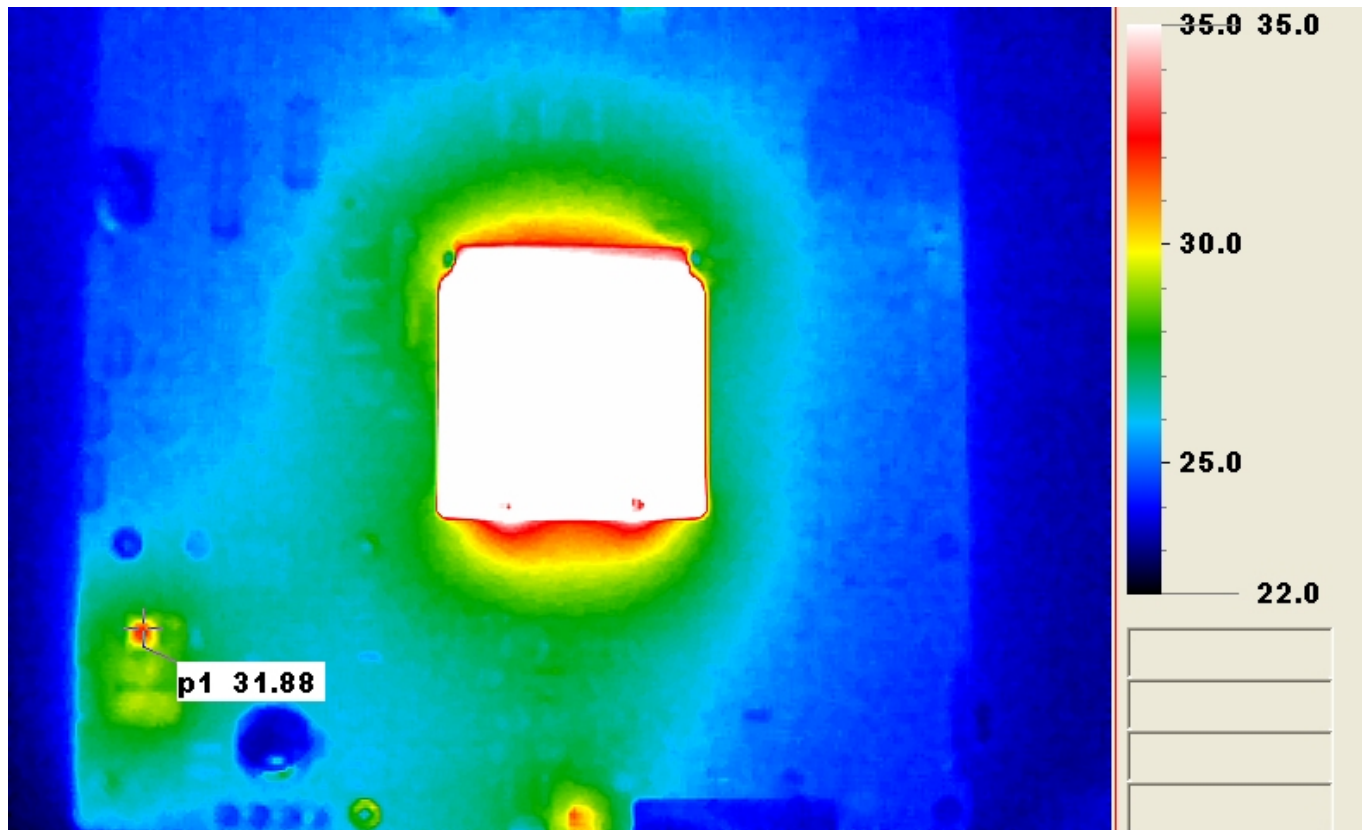
Test by DA-100: 24.8°C with Heat Sink
6. Take Picture Time:

After power on 2 hours

### Temperature Profile Test:

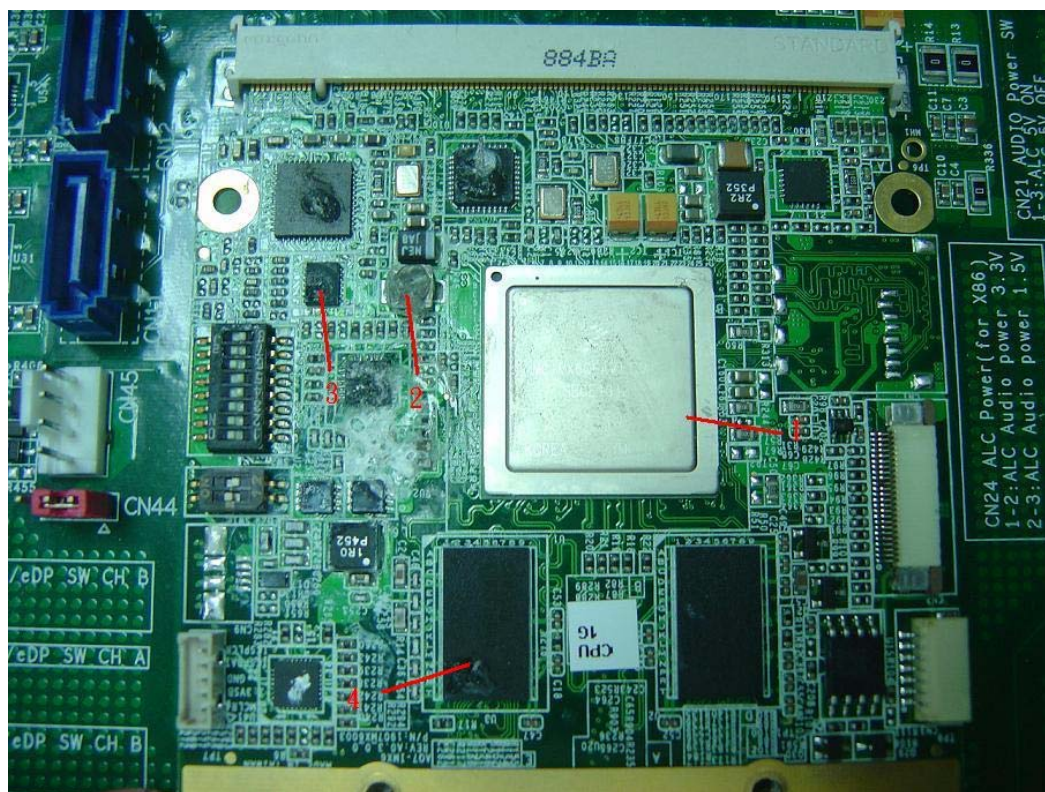
Component Side:

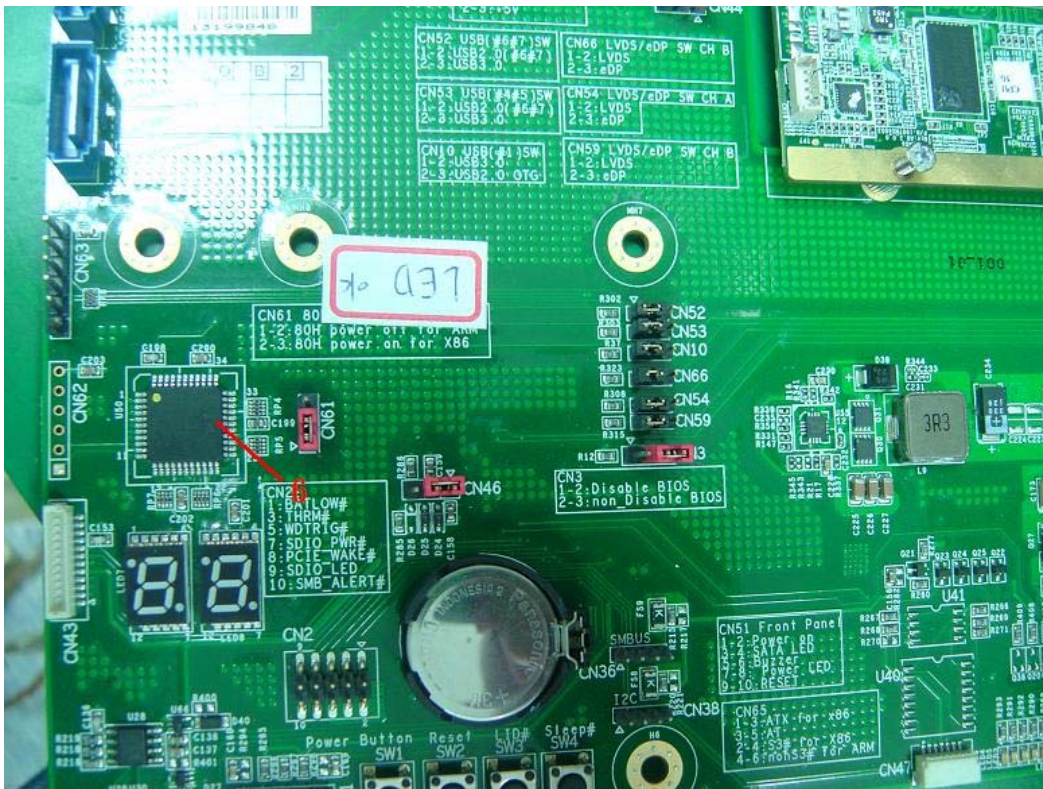




**Terminal Recorder:**

Measuring Thermal Couple Position :





## Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24.3°C	60°C	
1	U1	(TF)Freescale CPU.i.MX6 Quad.1GHz.FCPBGA.MCIMX6Q6AVT10AC	105	50.9	86.6	
2	L3	(TF)COIL.2.2uH.±20%.SMD.4.5*4*2.0mm.DCR=40mΩ.Irms=4Amp TRIO.EM-22AM01V01	105	57.0	92.7	
3	U19	(TF)IC.SMD.14P.5A/24V/500KHz.Step-Down Co.MPS NB634EL-LF-Z	125	54.0	89.7	
4	U3	(TF)IC.DDRIII-SDRAM.128M X 16(bit).1600MHz.1.5V.FBGA 96P.SMD.SAMSUNG.K4B2G1646Q-BCK0	95	48.1	83.8	
5	U5	(TF)IC.DDRIII-SDRAM.128M X 16(bit).1600MHz.1.5V.FBGA 96P.SMD.SAMSUNG.K4B2G1646Q-BCK0	95	49.4	85.1	
6	U50	(TF)IC.SMD.CPLD VQFP 44P.CS:A3B6.Xilinx.XC9536XL-10VQ44C	125	33.4	69.1	

**Note(\*):**

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

**3. Judgment Criteria:**

- **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
- **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.

**4. Defect NO.**